Surge Arrester

Material Data Sheet

Product Class	**LN8A-A*,LN8B-B*,LN8E-A* B88069X* (Tin plated)**
Date	**05/23/2024**
IMDS ID if available	
Version	**5.01**

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	**Substance**	TMPS**) [wt%]	**CAS if applicable**	**typical mass of material [wt-%]**	**Traces see 1)**
Active part	Ceramic	3B	Al2O3	100	1344-28-1	29	
	Metal	1C11	Cu	100	7440-50-8	65	
Brazing ring	Metal	4D	Ag	72	7440-22-4	3	
			Cu	28	7440-50-8		
Plating	Plating	1C8	Sn	100	7440-31-5	1	
Disc	Ceramic	3B	Al2O3	100	1344-28-1	1.5	
Glue	Adhesive	4B3	Hydroxyalkyl methacrylate	20	868-77-9	0.5	
			Acrylate	40	141-32-2		
			Methacrylic acid- β-Hydroxypropyl ester	10	27813-02-1		
			Tert butyl peroxide benzoate	10	614-45-9		
			2,2-dimethoxy-phenylethanone	10	24650-42-8		
			Acrylic acid	10	79-10-7		
					Sum of total	100	

sizes [mm]	**weight range[g]**	**part name**	**material numbers**
16.3 X 9.5 X 8.4	5.5	LN8A-A800DC-5	B88069X2863*
		LN8A-A1400DC-5	B88069X1003*
		LN8B-B1400DC-5	B88069X3053*
		LN8B-B1400DC-5	B88069X5303*
		LN8E-A1400DC-5	B88069X7443*

Not part of a Product Class	

Surge Arrester

Material Data Sheet

Product Class	**LN8A-A*,LN8B-B*,LN8E-A* B88069X* (Tin plated)**	
Date	**05/23/2024**	
IMDS ID if available		
Version	**5.01**	

Contact	Mohd Faizal Jamaludin	
Division	TDK ELECTRONICS (MALAYSIA) SDN BHD	
Address	11 Jalan Firma 3 Tebrau Ind IV, 81100 JB Malaysia	
	Tel: +60-7-3566629	mailto: mohdfaizal.jamaludin@tdk.com

*) others: .(not declarable or prohibited substances acc. GADSL)
**) typical mass percentage of substance

Important remarks:

1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.

2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid **)**

- ☑ **no exemptions;**
- ☐ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- ☐ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- ☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- ☐ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- ☐ Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- ☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- ☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- ☐ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- ☐ Other Exemption than above .....

